

ABSTRACT

This ultrasonic inspection device 1, for inspecting a packaged semiconductor device D, is provided with: an ultrasonic transducer 2 which outputs ultrasonic waves W2 to a semiconductor device D; a receiver (a reflection detection unit) 13 which detects reflected waves of the ultrasonic waves W reflected on the semiconductor device D; a stage 3 which moves the positions of the semiconductor device D relative to the ultrasonic transducer 2; a stage control unit 21 which controls driving of the stage 3; and an analysis unit 22 which analyzes the reaction of the semiconductor device D to the input of the ultrasonic waves W from the ultrasonic transducer 2. The stage control unit 21 controls the distance between the semiconductor device D and the ultrasonic transducer 2 on the basis of a peak occurring in time waveform K of the reflected wave detected by the receiver 13.

Figure 4